

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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TITLE: METHOD FOR MANUFACTURING VERY LOW ROUGHNESS
ELECTRODEPOSITED COPPER FOIL AND ELECTRODEPOSITED COPPER FOIL
MANUFACTURED THEREBY

Amendment A: CLAIM AMENDMENTS

Claims 1 - 15 (canceled).

16. (new) A method for manufacturing an electrodeposited copper foil comprising:

forming an electrolyte solution containing a sulfuric acid and a copper ion and a
chloride ion;

adding an additive to said electrolyte solution, said additive consisting of 6ppm to
100ppm of gelatin and 5ppm to 50ppm of hydroxyethyl cellulose and 0.05ppm to 20ppm of
bis(sodiumsulfopropyl)disulfide;

submerging a rotating drum and an anode plate in said electrolyte solution, said anode
plate having a curved shape and spaced by a distance from an outer surface of said drum; and

applying a negative current to said drum and a positive current to said anode plate so
to deposit the copper foil onto said outer surface of said drum.

17. (new) The method of Claim 16, said bis(sodiumsulfopropyl)disulfide being an amount
of between 0.5ppm to 3ppm.

18. (new) The method of Claim 16, the deposited copper foil having a matte side and a shiny

side, said matte side having a roughness greater than a roughness of said shiny side.

19. (new) the method of Claim 16, said gelatin having a molecular weight of greater than 10000.

20. (new) The method of Claim 16, said sulfuric acid being an amount of 50 to 200 g/l, said copper ion being in an amount of 30 to 150 g/l, said chloride ion of 200mg/l.

21. (new) The method of Claim 16, said electrolyte solution being at a temperature of between 20 and 80°C.

22. (new) The method of Claim 16, said electrolyte having a current density of between 20 and 150A/dm².